

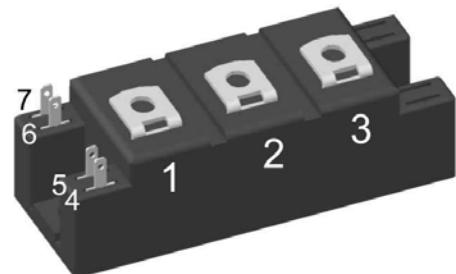
IGBT (NPT) Module

V_{CES} = 2x 1200 V
 I_{C25} = 135 A
 $V_{CE(sat)}$ = 2.2 V

Phase leg

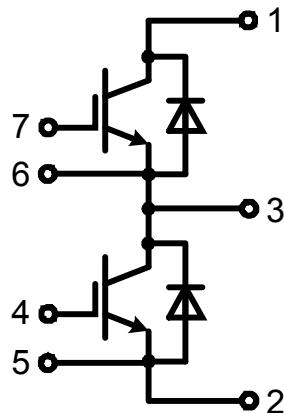
Part number

MII100-12A3



Backside: isolated

E72873



Features / Advantages:

- NPT IGBT technology
- low saturation voltage
- low switching losses
- switching frequency up to 30 kHz
- square RBSOA, no latch up
- high short circuit capability
- positive temperature coefficient for easy parallelling
- MOS input, voltage controlled
- ultra fast free wheeling diodes

Applications:

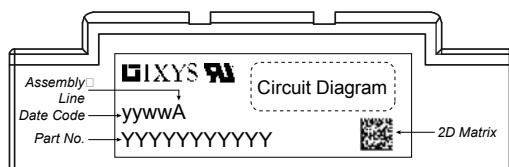
- AC motor drives
- Solar inverter
- Medical equipment
- Uninterruptible power supply
- Air-conditioning systems
- Welding equipment
- Switched-mode and resonant-mode power supplies
- Inductive heating, cookers
- Pumps, Fans

Package: Y4

- Isolation Voltage: 3600 V~
- Industry standard outline
- RoHS compliant
- Soldering pins for PCB mounting
- Base plate: DCB ceramic
- Reduced weight
- Advanced power cycling

IGBT			Ratings				
Symbol	Definition	Conditions	min.	typ.	max.	Unit	
V_{CES}	collector emitter voltage	$T_{VJ} = 25^\circ C$			1200	V	
V_{GES}	max. DC gate voltage				± 20	V	
V_{GEM}	max. transient gate emitter voltage				± 30	V	
I_{C25}	collector current	$T_c = 25^\circ C$			135	A	
I_{C80}		$T_c = 80^\circ C$			90	A	
P_{tot}	total power dissipation	$T_c = 25^\circ C$			560	W	
$V_{CE(sat)}$	collector emitter saturation voltage	$I_c = 75A; V_{GE} = 15 V$	$T_{VJ} = 25^\circ C$	2.2	2.7	V	
			$T_{VJ} = 125^\circ C$	2.7		V	
$V_{GE(th)}$	gate emitter threshold voltage	$I_c = 3mA; V_{GE} = V_{CE}$	$T_{VJ} = 25^\circ C$	4.5	5.5	6.5	V
I_{CES}	collector emitter leakage current	$V_{CE} = V_{CES}; V_{GE} = 0 V$	$T_{VJ} = 25^\circ C$		5	mA	
			$T_{VJ} = 125^\circ C$	7.5		mA	
I_{GES}	gate emitter leakage current	$V_{GE} = \pm 20 V$			300	nA	
$Q_{G(on)}$	total gate charge	$V_{CE} = 600 V; V_{GE} = 15 V; I_c = 75 A$		350		nC	
$t_{d(on)}$	turn-on delay time	inductive load $V_{CE} = 600 V; I_c = 75 A$ $V_{GE} = \pm 15 V; R_G = 15 \Omega$		100		ns	
t_r	current rise time			50		ns	
$t_{d(off)}$	turn-off delay time			650		ns	
t_f	current fall time			50		ns	
E_{on}	turn-on energy per pulse			12.1		mJ	
E_{off}	turn-off energy per pulse			10.5		mJ	
RBSOA	reverse bias safe operating area	$V_{GE} = \pm 15 V; R_G = 15 \Omega$	$T_{VJ} = 125^\circ C$				
I_{CM}		$V_{CEmax} = 1200V$			150	A	
SCSOA	short circuit safe operating area	$V_{CEmax} = 1200 V$					
t_{sc}	short circuit duration	$V_{CE} = 1200 V; V_{GE} = \pm 15 V$	$T_{VJ} = 125^\circ C$		10	μs	
I_{sc}	short circuit current	$R_G = 15 \Omega$; non-repetitive			270	A	
R_{thJC}	thermal resistance junction to case				0.22	K/W	
R_{thCH}	thermal resistance case to heatsink				0.22	K/W	
Diode							
V_{RRM}	max. repetitive reverse voltage	$T_{VJ} = 25^\circ C$			1200	V	
I_{F25}	forward current	$T_c = 25^\circ C$			150	A	
I_{F80}		$T_c = 80^\circ C$			95	A	
V_F	forward voltage	$I_F = 75A$	$T_{VJ} = 25^\circ C$		2.50	V	
			$T_{VJ} = 125^\circ C$		1.70	V	
I_R	reverse current	$V_R = V_{RRM}$	$T_{VJ} = 25^\circ C$		1	mA	
			$T_{VJ} = 125^\circ C$		1.5	mA	
Q_{rr}	reverse recovery charge	$V_R = 600 V$ $-di_F/dt = 600 A/\mu s$ $I_F = 75A; V_{GE} = 0 V$			7	μC	
I_{RM}	max. reverse recovery current				62	A	
t_{rr}	reverse recovery time				200	ns	
E_{rec}	reverse recovery energy				1.2	mJ	
R_{thJC}	thermal resistance junction to case				0.45	K/W	
R_{thCH}	thermal resistance case to heatsink				0.45	K/W	

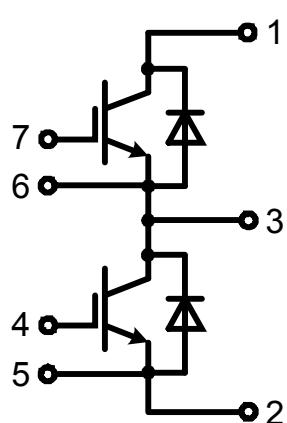
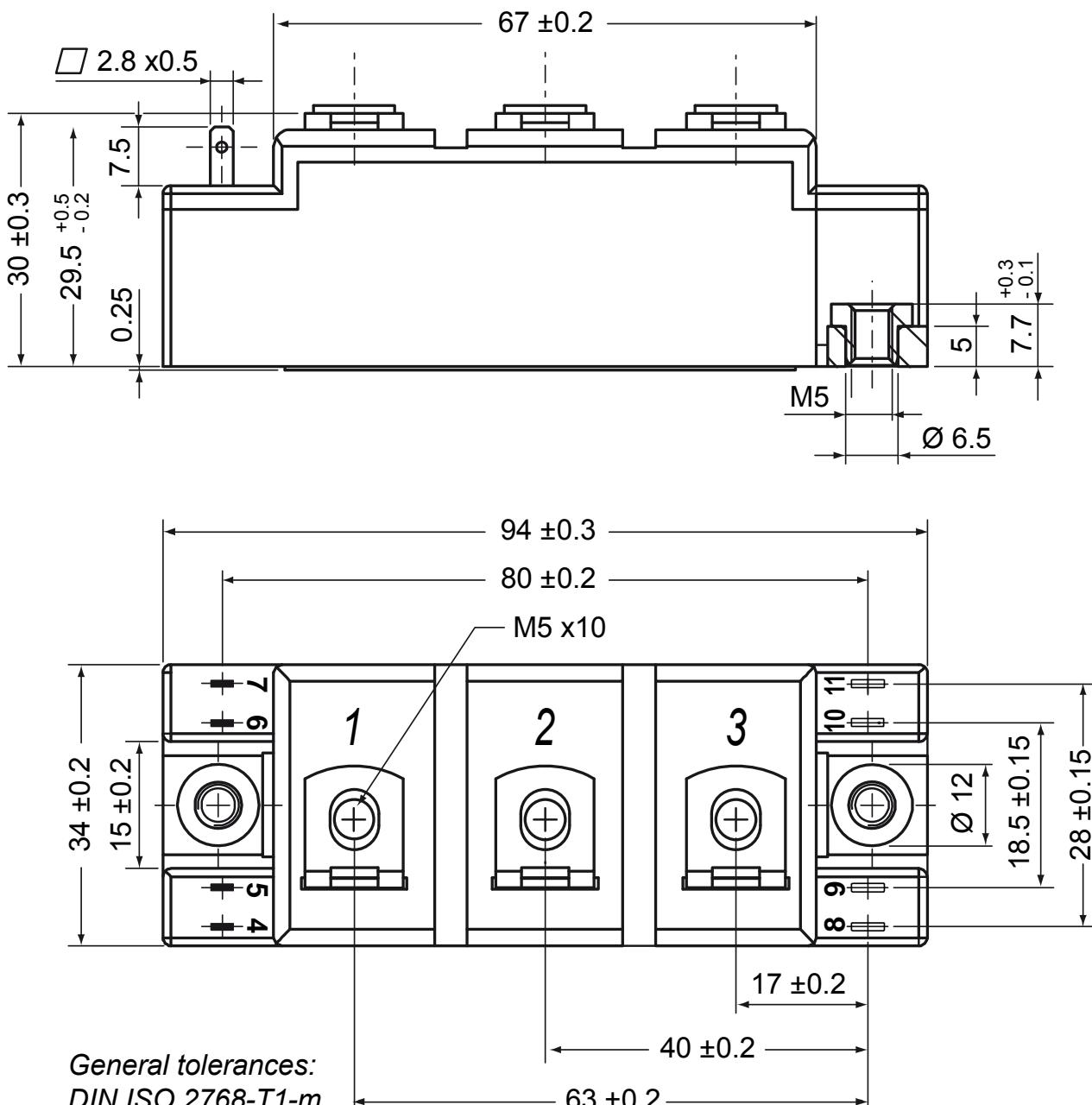
Package Y4			Ratings		
Symbol	Definition	Conditions	min.	typ.	max.
					Unit
I_{RMS}	RMS current	per terminal			300 A
T_{VJ}	virtual junction temperature		-40		150 °C
T_{op}	operation temperature		-40		125 °C
T_{stg}	storage temperature		-40		125 °C
Weight				110	g
M_D	mounting torque		2.25		2.75 Nm
M_T	terminal torque		4.5		5.5 Nm
$d_{Spp/App}$	creepage distance on surface striking distance through air		terminal to terminal	14.0	10.0 mm
$d_{Spb/Abp}$			terminal to backside	16.0	16.0 mm
V_{ISOL}	isolation voltage	t = 1 second t = 1 minute	50/60 Hz, RMS; $I_{ISOL} \leq 1$ mA		3600 V 3000 V



Ordering	Part Number	Marking on Product	Delivery Mode	Quantity	Code No.
Standard	MII100-12A3	MII100-12A3	Box	6	466743

Equivalent Circuits for Simulation		* on die level	$T_{VJ} = 150$ °C	
V_0	R_0		IGBT	Diode
$V_{0\max}$	threshold voltage		1.5	1.3 V
$R_{0\max}$	slope resistance *		13.6	6.5 mΩ

Outlines Y4



IGBT

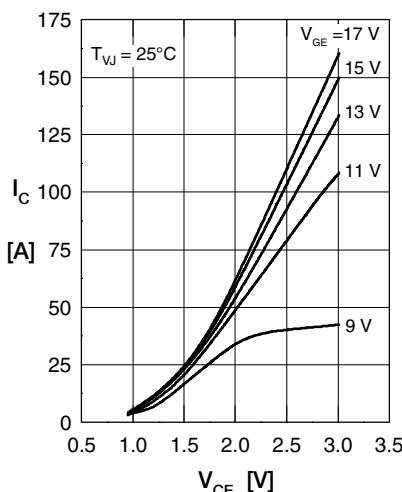


Fig. 1 Typ. output characteristics

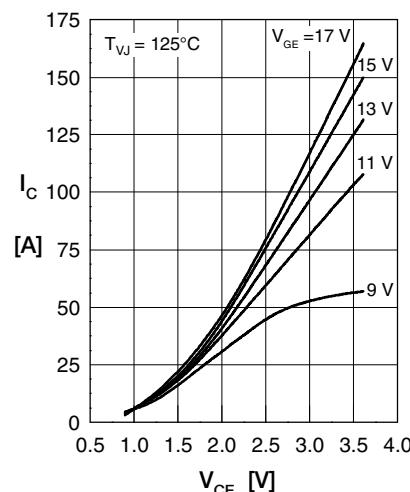


Fig. 2 Typ. output characteristics

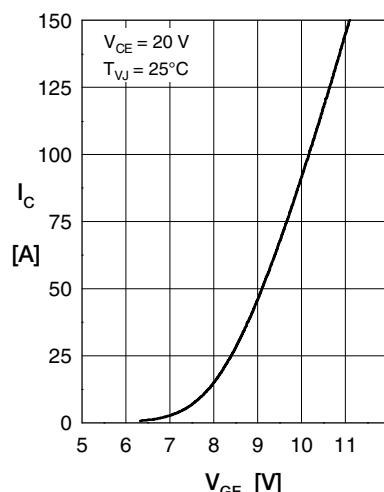


Fig. 3 Typ. transfer characteristics

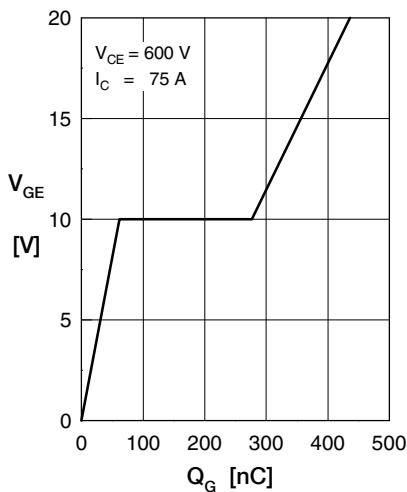


Fig. 4 Typ. turn-on gate charge

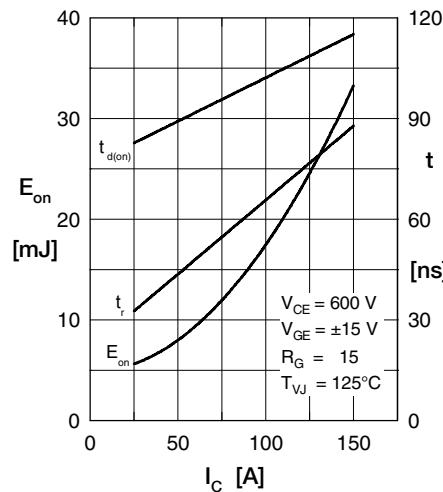


Fig. 5 Typ. turn on energy & switching times versus collector current

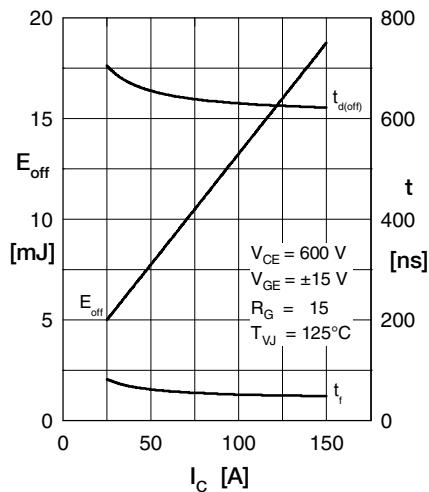


Fig. 6 Typ. turn off energy & switching times versus collector current

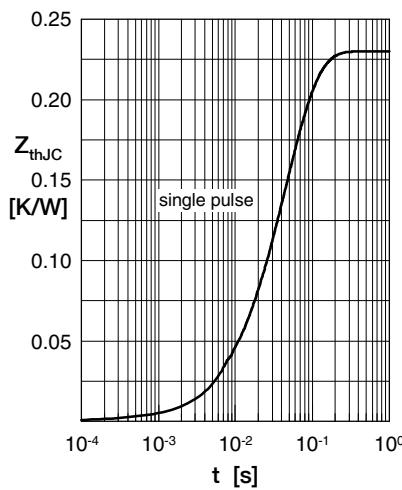


Fig. 12 Typical transient thermal impedance

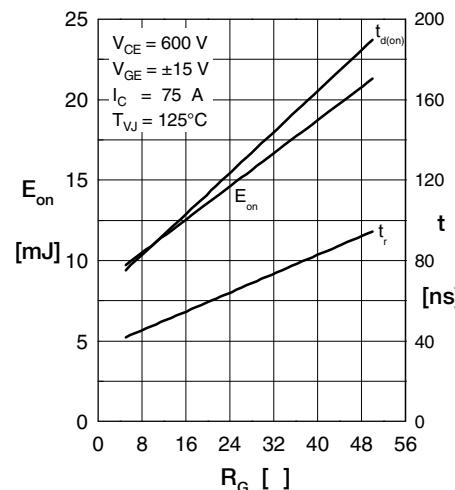


Fig. 9 Typ. turn on energy & switching times versus gate resistor

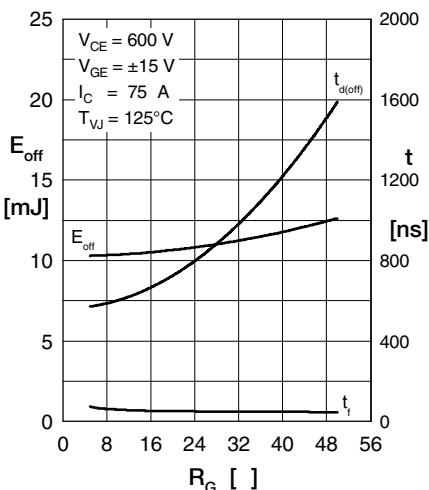


Fig. 9 Typ. turn off energy & switching times versus gate resistor

Diode

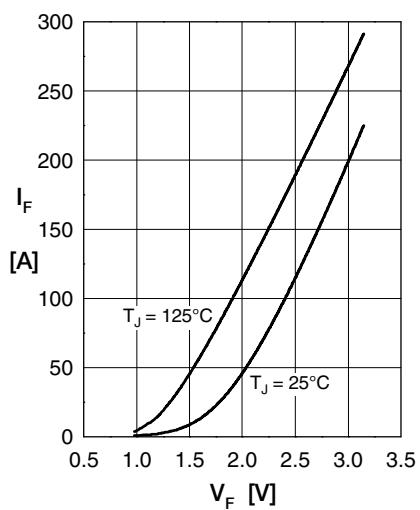
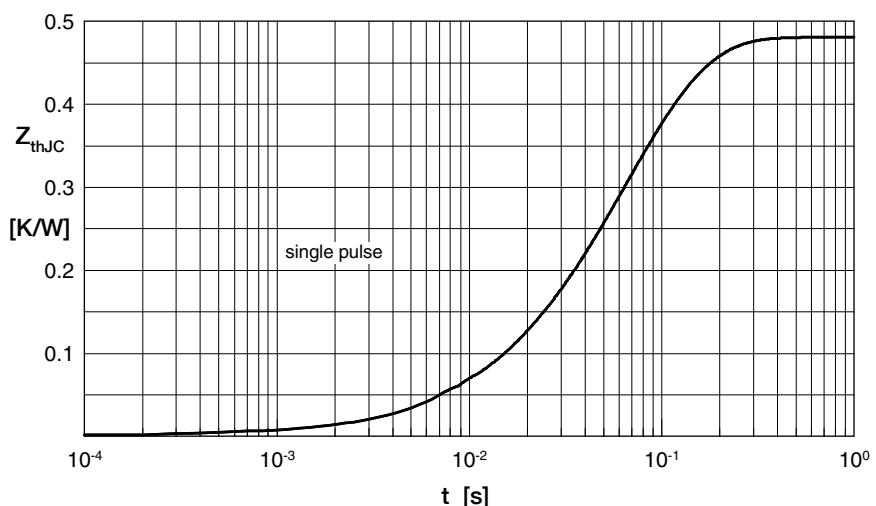
Fig. 1 Typ. Forward current vs. V_F 

Fig. 2 Typ. transient thermal impedance junction to case